G&P TECHNOLOGY

812L
Post-CMP Linear Cleaner

AXUS TECHNOLOGY

Your source for leading-edge surface processing solutions

The G&P Technology 812L cleaner can be used as a stand-alone post-CMP cleaning tool or as a perfect companion to the G&P Technology POLI-762 CMP tool. The G&P Technology 812L cleaner can be configured to use the same cleaning consumables set typically used on common CMP planarization tools. This provides a method for process testing using cleaning recipes similar to those used on full-scale integrated production tools. Integration with the POLI-762 provides for automated post-CMP transfer directly into the 812L cleaner's input station.

For cleaning process development and testing, the 812L can be equipped with an optional Friction and Force Measurement (FFM) system. This innovative system provides a built-in metrology system which allows users to measure contact and surface friction during the cleaning process for clear correlation between operating characteristics and cleaning performance. The FFM measurement also provides a quantitative measurement of consumables' performance allowing users to monitor process consistency. When added to the 812L, this system can help process engineers and cleaning specialists develop an optimized, predictable and repeatable robust polishing and cleaning process recipe.

FEATURES

- 200mm and 300mm wafer size
- 2 Double-sided PVA brushes
- Auto load
- Spin rinse dry output station

Options

- Megasonic Unit for enhanced cleaning
- Quick dump rinse (QDR-1, single tank
- Quick dump rinse (QDR-2, recycling
- Cleaner gripper option
- Integration to POLI-762
- Friction & Force Measurement

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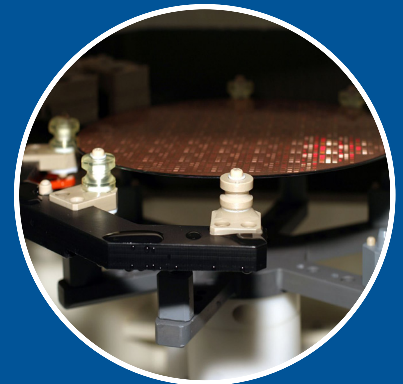
STANDARD CONFIGURATION - Model 812L	
Wafer size capacity	200mm and 300mm
Cleaning sequence	Auto load
	Pre-cleaning DI H_2O knife rinse
	1st double-sided PVA brush
	2nd double-sided PVA brush
	Spin rinse and dry (SRD)
Number of Brush Stations	2, double-sided PVA
Brush size	70 OD x 32 ID x 320 L
Rotating speed	30 to 300 rpm
Brush position adjustment angle	± 5°
Number of chemical inputs	2
Type (typical)	NH_4OH or DI H_2O
Chemical supply	4 spray nozzles and through the brush
Spin Station rotational speed	Up to 2500 rpm
Spin station rinse	DI H_2O
Blow off/Drying method	N2 blow off
Operator interface	Intuitive touch screen
Cleaning time (typical)	3-5 minutes per wafer

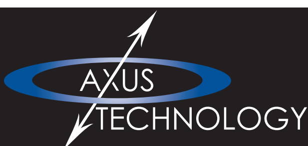
OPTIONS AVAILABLE	
Megasonic Unit	For enhanced cleaning action
Quick Dump Rinse (QDR-1)	Simple tank type
Quick Dump Rinse (QDR-2)	Recycling type
Cleaner Gripper option	8 and 12 inch
Integration to POLI-762	Automatic post-CMP transfer
Friction & Force Measurement	FFM system measures contact and surface friction during cleaning process

DIMENSIONS		
Metric	1970W x 975D x 1380H	
Inches	77.5W x 39D x 55H	
Weight	900 kg	1980 lbs

2 Double-sided PVA brushes

Spin Rinse Dry Output Station





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